



SEI-110-02-GF-S-E-TR

SEI-120-02-GF-S

SIBF-10-F-S-AD

SIBF-25-F-S-AD

SIBF-05-F-S-AD

(1,00 mm) .0394" (SEI) (1,27 mm) .050" (SIBF)

SEI, SIBF SERIES

ONE PIECE INTERFACE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEI

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au over 50µ" (1,27 µm) Ni
Current Rating: 2.3 A per pin (1 pin powered)
Operating Temp Range: -55°C to +125°C
Mating Force: 50g (0,49 N) per contact
Voltage Rating: 400 VAC
Cycles: 100 min
Contact Deflection: (0,46 mm) .018" nominal
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (05-25) (0,15 mm) .006" max (30)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



SEI	NO. OF POSITIONS	PLATING OPTION	S	INSERT OPTION	ALIGNMENT OPTION	OTHER OPTION
	05, 10, 15, 20, 25, 30 (Standard sizes)	-G = 10µ" (0,25 µm) Gold -GF = 3µ" (0,08 µm) Gold flash		Leave blank for Short Version (No screw down inserts or holes) -E = #2-56 x 1/16" screw thread -M = 2,00 mm x 0,40 mm screw thread	Leave blank for no Alignment Pin -AT = Alignment Pin Top Side -AB = Alignment Pin Bottom Side	-TR = Tape & Reel

SEI Dimensions:
 No. of positions x (1,00) .03937 + (0,41) .016
 (6,10) .240 (4,95) .195
 01 SHORT VERSION
 (1,65) .065 (0,31) .012
 ((No. of positions-1) x (1,00) .03937) + (7,62) .300
 (3,43) .135
 Threaded Insert (2)

SIBF Dimensions:
 No. of positions x (1,27) .050 + (0,43) .017
 (6,25) .246 (7,50) .295
 (1,27) .050 (0,70) .028
 (4,00) .158 (3,00) .118
 No. of positions x (1,27) .050 - (3,81) .150

Options:
 -AT OPTION: (0,89) .035 DIA (1,27) .050 (4,32) .170
 -AB OPTION: (0,89) .035 DIA (4,32) .170

Other Options:
 -F = Flash Gold, Matte Tin on tail
 -AD = Top & Bottom Alignment Pin

Threaded insert option: RUGGEDIZED by SAMTEC

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SIBF

Insulator Material: Black Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 2.5 A per pin (1 pin powered)
Operating Temp Range: -55°C to +125°C
Voltage Rating: 155 VAC
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (05-20) (0,15 mm) .006" max (25)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



SIBF	NO. OF POSITIONS	PLATING OPTION	S	OPTION
	-05, -10, -20, -25	-F = Flash Gold, Matte Tin on tail		-AD = Top & Bottom Alignment Pin

SIBF Dimensions:
 No. of positions x (1,27) .050 + (0,43) .017
 (6,25) .246 (7,50) .295
 (1,27) .050 (0,70) .028
 (4,00) .158 (3,00) .118
 No. of positions x (1,27) .050 - (3,81) .150

Options:
 -AD OPTION: (1,00) .040

SIBF 3 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	7 GHz / 14 Gbps
Differential Pair Signaling	7.5 GHz / 15 Gbps

*Test board losses de-embedded from performance data. Performance data for other stack heights and complete test data available at www.samtec.com?SIBF or contact sig@samtec.com

ALSO AVAILABLE (MOQ Required)

- Additional positions
- Top or bottom side only alignment pin

Contact Samtec.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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